

Amendments To The Claims:

This listing of claims replaces all prior versions of claims in the application.

**Listing of Claims**

1. (previously presented) A method of processing a specimen comprising:
  - a first step of etching a specimen, which is a lamination layer formed on a substrate and includes at least one layer made of NiFe alloy or NiFeCo alloy, by gas plasma with a gas which contains chlorine at a temperature of the specimen below 200°C in an etching chamber;
  - a second step, which is performed immediately after said first step, of removing a residual chlorine component deposited on an exposed portion of said lamination layer during said first step, and eliminating debris deposited on a side wall thereof by rinsing the same using at least one liquid; and
  - a third step of drying the specimen immediately after the rinsing thereof by placing the specimen on a hot plate and by heating the specimen at a temperature below 200°C.
2. (currently amended) A method of processing a specimen according to claim 1, wherein said second step is and third steps are executed in continuous succession after said first step in the same apparatus.
3. (previously submitted) A method of processing a specimen according to claim 1, wherein said gas plasma is generated using at least one of Cl<sub>2</sub>, BCl<sub>3</sub>, Ar and O<sub>2</sub> gases, or a combination thereof.

4. (previously presented) A method of processing a specimen according to claim 1, wherein said second step of liquid rinsing includes one or more than two of the following steps:

- (A) pure water rinsing,
- (B) alkaline liquid cleaning followed by water rinsing,
- (C) acidic liquid cleaning followed by water rinsing, and
- (D) neutral detergent cleaning followed by water rinsing.

5. (canceled)

6. (previously presented) A method of processing a specimen according to claim 1, wherein a temperature of the liquid is controlled.

7. (previously presented) A method of processing a specimen according to claim 1, wherein said lamination layer includes, in addition to said NiFe or NiFeCo alloys, at least one or more of the following layers which are to be etched by gas plasma in the etching chamber:

- (A) photo resist layer,
- (B) alumina (Al<sub>2</sub>O<sub>3</sub>) layer,
- (C) silicon oxide layer,
- (D) Cu layer,
- (E) Ta layer, and
- (F) Cr layer.

8. (previously presented) A method of processing a specimen according to claim 1, wherein the substrate is a sintered substrate comprising Al<sub>2</sub>O<sub>3</sub> and TiC, and on the substrate a layer of NiFe or NiFeCo alloy is formed, which is to be etched in the etching chamber.

Claims 9 - 11. (canceled)

12. (withdrawn) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite thereto and including a multiple layer resist etching thereof, comprising the steps of:

forming a lamination layer comprising an upper photo resist layer, a hard mask layer made of SiO<sub>2</sub> or alumina, a lower photo resist layer, and a seed layer made of NiFe or NiFeCo alloy;

plasma-etching said hard mask layer using said upper photo resist layer as its mask;

plasma-etching said lower photo resist layer to form a deep groove therein using a gas which contains chlorine with said hard mask used as its mask until said seed layer is exposed in the bottom of said deep groove;

removing a residual chlorine component deposited on an exposed surface of said seed layer by rinsing with a liquid;

drying after removal of said residual chlorine component; and

embedding NiFe alloy into said deep groove to connect with said seed layer thereby forming said upper magnetic pole.

13. (previously presented) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite thereto and including a seed layer processing thereof, comprising the steps of:

forming a lamination layer comprising a seed layer made of NiFe or NiFeCo alloy, an upper magnetic pole made of NiFe alloy contacted to said seed layer, a gap layer made of an oxide such as alumina or silicon oxide in contact with said seed layer, and a shield layer made of NiFe alloy in contact with said gap layer;

plasma-etching said seed layer using a gas which contains chlorine with said upper magnetic pole used as its mask;

removing a residual chlorine component by liquid rinsing immediately after said plasma-etching step; and

drying the rinsed body immediately after said removing step by heating at a temperature below 200 °C after placing the same on a hot plate.

14. (previously presented) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite thereto and including a gap layer processing thereof, comprising the steps of:

forming a lamination layer comprising a seed layer made of NiFe or NiFeCo alloy, an upper magnetic pole made of NiFe alloy contacted to said seed layer, a gap layer made of an oxide film in contact with said seed layer, and a shield layer made of NiFe alloy in contact with said gap layer;

etching said seed layer;

etching said gap layer by plasma processing using a gas which contains

chlorine or fluorine with said upper magnetic pole used as its mask;  
removing a residual chlorine and/or fluorine components by liquid rinsing  
immediately after said gap layer etching step; and  
drying the rinsed body formed by the above steps by heating at a temperature  
below 200 °C after placing the same on a hot plate.

15. (previously presented) A method of manufacture of a magnetic head having  
an upper magnetic pole and a lower magnetic pole disposed opposite thereto and  
including a trim-processing thereof, comprising the steps of:

forming a lamination layer comprising a seed layer made of NiFe or NiFeCo  
alloy, an upper magnetic pole made of NiFe alloy contacted to said seed layer, a gap  
layer made of an oxide film in contact with said seed layer, and a shield layer made  
of NiFe alloy in contact with said gap layer;

etching said seed layer;

etching said gap layer;

trim-etching said shield layer using a gas which contains chlorine by plasma  
processing with said upper magnetic pole used as its mask;

removing a residual chlorine component by liquid rinsing immediately after  
said trim-etching step; and

drying the rinsed body immediately after said removing step by heating at a  
temperature below 200 °C after placing the same on a hot plate.

16. (previously presented) A method of manufacture of a magnetic head having  
an upper magnetic pole and a lower magnetic pole disposed opposite thereto,

comprising the steps of:

forming a lamination layer comprising a seed layer made of NiFe or NiFeCo alloy, an upper magnetic pole made of NiFe alloy contacted to said seed layer, a gap layer made of an oxide film in contact with said seed layer, and a shield layer made of NiFe alloy in contact with said gap layer;

plasma-etching said seed layer, said gap layer and said shield layer consecutively with said upper magnetic pole used as a mask; and

applying a corrosion prevention treatment, which is performed immediately after said plasma-etching step, for removal of a residual chlorine component deposited on an etched surface thereof, including rinsing of the body to be treated and drying the same by heating at a temperature below 200°C after placing the same on a hot plate.

17. (previously presented) A method of manufacture of a magnetic head according to claim 16, wherein said gap layer is etched by gas plasma containing fluorine, said seed layer and said shield layer are etched by gas plasma containing chlorine and argon, and wherein said the rinsing in said corrosion prevention treatment is carried out liquid.

18. (previously presented) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite to each other, comprising the steps of:

forming a lamination layer comprising a seed layer made of NiFe or NiFeCo alloy, an upper magnetic pole made of NiFe alloy contacted to said seed layer, a gap

layer made of an oxide film in contact with said seed layer, and a shield layer made of NiFe alloy in contact with said gap layer;

plasma-etching said seed layer and said gap layer consecutively with said upper magnetic pole used as a mask; and immediately thereafter,

applying a corrosion prevention treatment for removal of a residual chlorine component deposited on an etched surface thereof, including rinsing of the body to be treated and drying the same by heating at a temperature below 200 °C after placing the same on a hot plate.

19. (previously presented) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite to each other for manufacturing said upper magnetic pole thereof, comprising the steps of:

forming a lamination layer comprising an upper magnetic pole layer made of NiFe alloy, and a mask layer of a photo resist or an oxide film made of alumina or silicon oxide film which is laminated on said upper magnetic pole;

plasma etching said upper magnetic pole using said mask layer as its mask; and immediately thereafter,

applying a corrosion prevention treatment for removal of a residual chlorine component deposited on an etched surface thereof, including rinsing of the body to be treated and drying the same by heating at a temperature below 200 °C after placing the same on a hot plate.

20. (previously presented) A method of manufacture of a magnetic head having an upper magnetic pole and a lower magnetic pole disposed opposite to each other

and including a process for manufacture of said upper magnetic pole thereof,  
comprising the steps of:

forming a lamination layer comprising, sequentially from above,  
(A) a photo resist film,  
(B) an oxide film layer made of alumina or silicon oxide,  
(C) an upper magnetic pole layer made of NiFe alloy,  
(D) a seed layer made of NiFeCo alloy for bonding said NiFe alloy,  
(E) a gap layer made of an oxide film of alumina or silicon oxide, and  
(F) a shield layer made of NiFe alloy;

carrying out the following plasma etching steps in continuous succession,  
(Step 1) etching said oxide film layer using said mask layer as its mask,  
(Step 2) etching said upper magnetic pole layer using said 5 oxide film layer as it  
mask,  
(Step 3) etching said seed layer using said upper oxide film layer or said upper  
magnetic pole layer as its mask,  
(Step 4) etching said gap layer using said upper oxide film layer and said upper  
magnetic pole layer as its mask, and  
(Step 5) trim-etching said shield layer using said upper oxide film layer and said  
upper magnetic pole layer; and immediately thereafter,

applying a corrosion prevention treatment for removing a residual chlorine  
component deposited on an etched surface thereof, including rinsing of the body to  
be treated and drying the same by heating at a temperature below 200 °C after  
placing the same on a hot plate.

21. (previously presented) A method of manufacture of a magnetic head according to claim 20, comprising carrying out any steps of said plasma etching steps 1-5 in succession, then immediately thereafter applying said corrosion prevention treatment for removal of the residual chlorine component deposited on the etched surface thereof.

22. (previously presented) A method of manufacture of a magnetic head according to claim 20, comprising carrying out the rinsing/drying process immediately thereafter each step of said plasma etching steps 1-5 for removing a residual chlorine component and a debris on a side wall, said rinsing/drying process being executed in continuous succession within a single unit.

23. (previously presented) A method of manufacture of a magnetic head according to claim 20, wherein, in order for a selectivity ratio between each mask and its under-layer to become large during each plasma etching step, said etching process (1) is executed using a gas which contains mainly  $\text{BCl}_3$  or fluorine, said etching processes (2) and (3) are executed using a gas which contains mainly chlorine, said etching process (4) is executed using a gas which contains mainly  $\text{BCl}_3$  or fluorine, and said etching process (5) is executed using a gas which contains mainly chlorine, respectively.